

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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CM3312R111R-10

UNCONTROLLED DOCUMENT

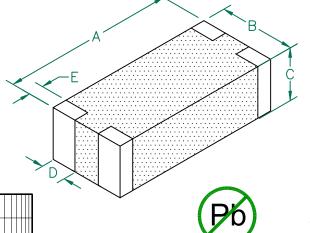
PHYSICAL DIMENSIONS:

 $8.50 [.335] \pm 0.25 [.010]$ 3.05 [.120] ± 0.25 [.010]

 $2.36 [.093] \pm 0.25 [.010]$

1.14 [.045] ± 0.13 [.005]

0.58 [.023] ± 0.18 [.007]



COMMON	COMMON MODE ELECTRICAL CHARACTERISTICS:									
COMMON MO © 100 MHz(DE Z Ω)	COMMON MODE Z © 500 MHz(Ω)		DCR (Ω)	CONTINOUS Rated Current					
Nominal	110	Nominal (Ref)	150							
Minimum	83		-							
Maximum	138		_	0.005	5,000 mA					

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 13" REELS, 2500 PCS/REEL.
- 2. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 3. U.S. PATENT 6,288,626 SHOULD APPEAR ON THE LABEL OF EACH REEL OF PACKAGED PARTS.
- 4. TERMINATION FINISH IS 100% TIN.

REFLOW SOLDERING

[482]

PRE-HEATING

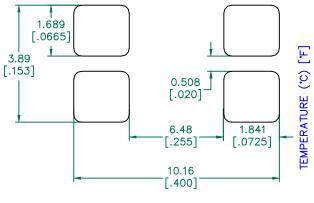
100 SECONDS

300 250 200 **IMPEDANCE** 150 50 100 1000 10000

Common

Z vs. FREQUENCY (C,N,O)

LAND PATTERNS FOR REFLOW SOLDERING



130 [266] 60 SECONDS

RECOMMENDED SOLDERING CONDITIONS

SOLDERING

5 - 10 SECONDS

60 SECONDS

MUST NOT

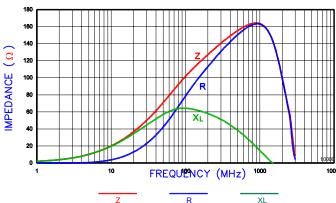
100	I		
80		R	DURING AND AFTER SOLDERING OPERATION SOLDER M
60			BE ALLOWED TO BRIDGE CONTACTS. CONTACT SEPARA MAINTAINED.
40		XL .	DIMENSIONS ARE



		DIMENSIONS ARE IN mm [INCHE	THIS DOCUMENT CONTAINS INFORMATION WHICH IS PROPRIETARY AND						
					THIS DOCUMENT IN WHOLE OR IN PART SHALL BE MADE WITHOUT WRITTEN AUTHORIZATION FROM STEWARD.				
					Steward				
)					PROJECT/PART NUMBER: CM3312R111R—10	REV	PART TYPE		DRAWN BY:
						SCALE: N	ITS [SHEET:	UKK
	A REV	ORIGINAL DRAFT DESCRIPTION	07/27/05 DATE	JRK	CAD #	TOOL #	3312	2	of 2

Z. R. XL vs. FREQUENCY

FREQUENCY (MHz)



AGILENT E4991A RF Impedance/Material Analyzer HP 16194A Test Fixture. TEST REF. 4979